

### REMARKS

Claims 6, 13-17, 19-25, 27, 28, 30 and 31 stand finally rejected. The Examiner is respectfully requested to reconsider and withdraw the rejections in view of the remarks herein.

#### Rejection of Claims under 35 U.S.C. § 102(b)

Claim 6 is rejected under 35 U.S.C. 102(b) anticipated by U.S. Patent No. 6,300,679 to Mukerji. This rejection is respectfully traversed.

Claim 6, as amended herein, includes the features of a form standard that is provided as a rigid mandrel and that is initially disposed above the upper surface of the second CSP, the form standard defining a standard sized form, and a flex circuit that is at least partially disposed about the form standard subsequent to the form standard being disposed above the upper surface of the second CSP, the form standard defining a cross-sectional shape of the flex circuit. Accordingly, claim 6 describes a rigid form standard, about which a flex circuit can be disposed to define a cross-section shape of the flex circuit.

As discussed in Applicants' previous response, Mukerji describes a flexible substrate for packaging a semiconductor component. A layer of conductive traces are formed on the substrate. An electrically insulating layer or mask can be applied over the traces to prevent the traces from directly contacting a semiconductor chip (see col. 4, lines 16-22). More specifically, the substrate having the trace and mask layers formed thereon, is folded around a semiconductor chip (see col. 4, lines 4-8).

The Examiner has asserted that the mask layer 512 of Fig. 5 is a form standard. This assertion, however, is incorrect. The mask layer of Mukerji is a flexible, electrical insulation layer that is applied over the traces to prevent the traces from directly contacting the semiconductor chip. Having applied the mask layer to the flat substrate, the substrate is subsequently folded around the semiconductor, with the mask layer correspondingly flexing as the substrate is folded. Consequently, the mask layer is necessarily flexible, and does not provide a rigid mandrel that forms the shape of the folded substrate. Accordingly, the mask layer is not a form standard that defines a standardized form, and is instead a simple insulation layer.

In view of the foregoing, Mukerji does not disclose a form standard that is provided as a rigid mandrel and that is initially disposed above the upper surface of the second CSP, the form standard defining a standard sized form, and also does not disclose a flex circuit that is at least partially disposed about the form standard subsequent to the form standard being disposed above the upper surface of the second CSP, the form standard defining a cross-sectional shape of the flex circuit. Consequently, Mukerji fails to describe each and every element as set forth in claim 6, and does not disclose the identical invention in as complete detail as is contained in claim 6, as required when applying a reference under §102(b). Therefore, reconsideration and withdraw of the rejection are respectfully requested.

*Rejection of Claims under 35 U.S.C. § 103(a)*

Claims 13-31 are rejected under 35 U.S.C. 103(a) as being unpatentable over Mukerji in view of Karabatsos. This rejection is respectfully traversed.

Applicants again remind the Examiner that claims 18, 26 and 29 had previously been cancelled without prejudice or disclaimer of the subject matter therein. Accordingly, the Examiner's current rejection of claim 18, 26 and 29 is moot.

Each of claims 13-17, 19-25, 27, 28, 30 and 31 ultimately depends from claim 6, which defines over the asserted reference, as discussed in detail above. Consequently, each of claims 13-17, 19-25, 27, 28, 30 and 31 also define over the asserted reference for at least the same reasons. Therefore, reconsideration and withdrawal of the rejections are respectfully requested.

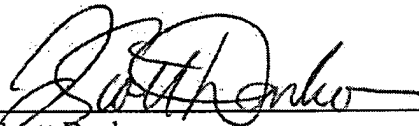
### CONCLUSION

It is believed that all of the pending claims have been addressed. However, the absence of a reply to a specific rejection, issue or comment does not signify agreement with or concession of that rejection, issue or comment. In addition, because the arguments made above may not be exhaustive, there may be reason for patentability of any or all pending claims (or other claims) that have not been expressed. Finally, nothing in this paper should be construed as an intent to concede any issue with regard to any claim, except as specifically stated in this paper, and the amendment of any claim does not necessarily signify concession of unpatentability of the claim prior to amendment. Applicants respectfully request consideration of all filed IDS' not previously considered, by initialing and returning each Form 1449.

No charges are believed due. However, if any fees are due, they are being paid concurrently herewith on the Electronic Filing System (EFS) by way of Deposit Account authorization. Please apply all charges or credits to Deposit Account No. 06-1050, referencing Attorney Docket No. 21260-021001.

Respectfully submitted,

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